Tool ID: 222
Tool Location: 111

Equipment Information Sheet

YES EcoClean Asher

Manager: Philip Schneider 607-254-4931
Backup: Jeremy Clark 607-254-6487
Backup: Aaron Windsor 607-254-4831

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY

- Wafers may be hot after processing. Tool has an automatic 60 second delay before door is unlatched.

USAGE RESTRICTIONS

SCHEDULING/SIGN-UP RESTRICTIONS

Minimum Tool Time: 15 minutes

Contact the tool manager to schedule if you want to process wafers other than 4"

MATERIALS COMPATIBILITY CATEGORY

Tool Category 2: Silicon Based Substrates and Select Refractory Metals

Allowed	Not Allowed
Tool category 1/1E materials	No Glass Substrates
Silicon Based Materials only	No CNF Class A or Class B metals and oxides/compounds of (exposed or buried) (ie Magnesium, Zinc, Barium, Calcium)
Si, SiC, SiO_2 substrates	
All Furnace grown or deposited films	
PECVD Films	No Gold, Silver or Copper (Exposed or buried)
ALD dieletric films	No High Vapor pressure materials
CNF Refractory Metals (ie Al, Ti,Ta,W,Pt,Mo,Cr,Ni)	No III/V Compound Semiconductors
Nitrides and Oxides of above metals	No Organic/Biology Molecules prepared-with or without Salt buffers
Cured organics and baked Photoresist	

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- No SU-8
- III/V substrates allowed.

Last Updated: 03/26/2025